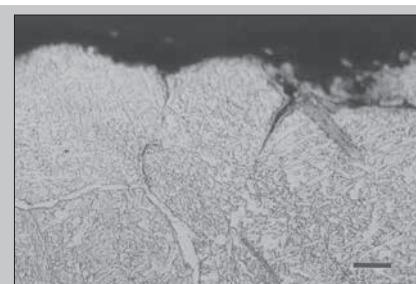


# Technical Information Guide: Compression Mounting Compounds

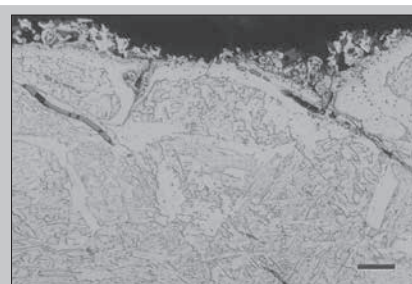
## CHARACTERISTICS OF COMPRESSION MOUNTING COMPOUNDS

| Materials     | General Purpose   | Best Edge Retention; Very Low Shrinkage   | Near Zero Electrical Resistance SEM - EDS/WDS                                       | Clear   |
|---------------|---|---|---|---|
| Ceramics      | PhenoCure™  | EpoMet™ F (Fine) or EpoVit™   | ProbeMet™   | TransOptic™   |
| Steels        | PhenoCure   | EpoMet G (Granular) or EpoVit   | ProbeMet  | TransOptic  |
| Plated Layers | PhenoCure   | EpoMet G or EpoVit  | ProbeMet  | TransOptic  |
| Aluminum      | PhenoCure   |   | ProbeMet  | TransOptic  |
| Copper/Brass  | PhenoCure   |   | ProbeMet  | TransOptic  |
|               |  |  |  |  |
| Color         | Black, Red or Green   | Black   | Copper  | Transparent   |
| Temperature   | 300°F [150°C]   | 300°F [150°C]   | 300°F [150°C]   | 350°F [177°C]   |
| Pressure      | 4200 psi [290 bar]  | 4200 psi [290 bar]  | 4200 psi [290 bar]  | 2100 psi [145 bar]  |

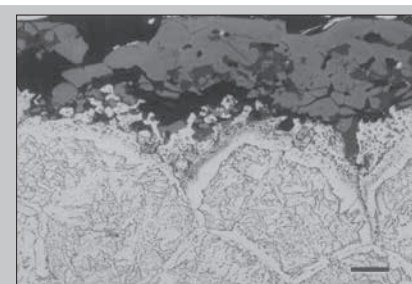
## Comparison of Six Edge Retention Compression Mounting Compounds



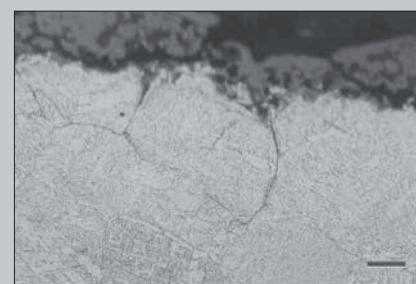
PhenoCure phenolic resin



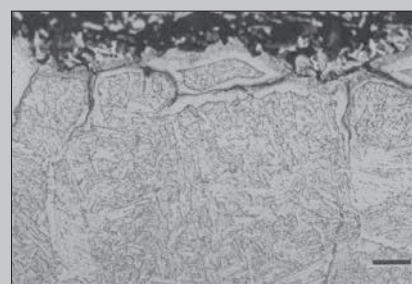
EpoMet thermosetting epoxy resin



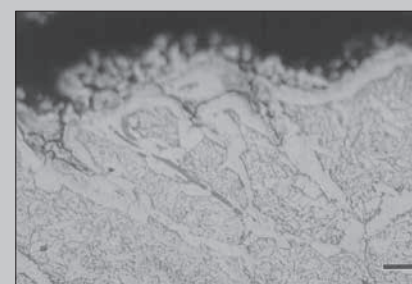
ProbeMet Cu-filled conductive resin



KonductoMet C-filled conductive resin



EpoxiCure cast epoxy resin with Conductive Filler particles



SamplKwick cast acrylic resin with Conductive Filler particles

Micrographs showing the as-forged surface of a hardened modified 5130 alloy steel part mounted using a variety of resins showing different degrees of edge retention. The specimens were polished simultaneously in the same holder and were etched with 2% nital. The magnification bars are 20 µm long. Best results were obtained with EpoMet, ProbeMet and EpoxiCure resin with the Conductive Filler particles.








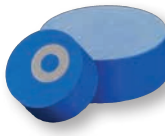

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




# Technical Information Guide: Compression Mounting Compounds

## COMPRESSION MOUNTING COMPOUNDS: COMPRESSION GUIDE



| Thermosetting Phenolics   |   | Thermosetting Epoxy   |   |   | Thermosetting Diallyl Phtalate  | Thermoplastic Acrylic   |
|---|---|---|---|---|---|---|
| <b>PhenoCure™</b><br>(Black, Red, Green)  | <b>KonductoMet™</b>   | <b>EpoMet™</b><br>(F = Fine, G = Granular)  | <b>EpoVit™</b>  | <b>ProbeMet™</b>  | <b>Diallyl Phtalate</b><br>(Mineral and Glass)                                      | <b>TransOptic™</b>  |
|  |  |  |  |  |  |  |
| For general use, most economical  | Carbon filled   | Best Edge Retention   | Best Edge Retention   | Copper filled   | Chemical Resistance   | Transparent   |
| Fast cycle time   | High Conductivity   | Chemically resistant  | Chemically resistant  | High Conductivity   | Good Edge Retention   | Longer cycle time   |
| Highest shrinkage   | Eliminates interference from Cu in compositional analysis                           | Lowest Shrinkage  | Lowest Shrinkage  | Lowest Shrinkage  | Moderate Shrinkage  | Lower Pressure  |
| Lower Hardness (88 Shore D)   | Lower Hardness (88 Shore D)   | Highest Hardness (95 Shore D)   | Highest Hardness (94 Shore D)   | Highest Hardness (94 Shore D)   | Highest Hardness (91 Shore D)   | Highest Hardness (80 Shore D)   |
| Black/Red/Green   | Black   | Black   | Black   | Copper  | Blue  | Transparent   |

## COMPRESSION MOUNTING COMPOUNDS- TROUBLESHOOT GUIDE

### Thermosetting Resins (Epoxies, Diallyl Phthalates and Phenolics)

| Defect   | Probable Cause  | Suggested Remedy   |
|--|---|--|
|  Radial splits or cracks          | Specimen cross sectional area too large; specimen with sharp corners                            | Use a larger mold size; decrease the specimen size; bevel sharp corners, if possible                                   |
|  Shrinkage gaps                   | Specimen surfaces dirty; specimen cooled quickly after polymerization; wrong resin used         | Clean and dry specimens carefully; after polymerization, cool under pressure to near ambient; use EpoMet G or EpoMet F |
|  Circumferential cracks           | Resin contained moisture  | Keeps resins dry during storage; keep containers closed when not using; dry resin by baking at 100-120°F [38-49°C]     |
|  Bulging or soft mount            | Inadequate curing (polymerization) time   | Increase polymerization time and pressure  |
|  Mount appears grainy and unfused | Time at temperature too short; temperature for polymerization too low; molding pressure too low | Increase polymerization time, temperature and pressure   |

### Thermosetting Resins (Acrylics)

|  |  |   |
|--|--|---|
|  Cottonball | Incomplete polymerization of resin; not enough time at temperature | Use less resin; use longer heating and cooling periods; use controlled linear cooling |
|  Crazing    | Relief of internal stresses upon ejection of mount                 | Cool mount to a lower temperature before ejection; use controlled linear cooling      |



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